

Amendments to the Abstract

Please amend the abstract as follows.

ABSTRACT OF THE DISCLOSURE

A substrate polishing apparatus polishes a surface of a substrate such as a semiconductor wafer to a flat mirror finish. The substrate polishing apparatus ~~according to the present invention~~ has a rotatable table having a polishing pad for polishing a semiconductor ~~substrate~~, substrate and a light emission and reception device for emitting measurement light through a through hole formed in the polishing pad to the semiconductor substrate and receiving reflected light from the semiconductor substrate so as to measure a film on the semiconductor ~~substrate~~, and substrate. The substrate polishing apparatus also has a supply passage for supplying a fluid to a path of the measurement light. The supply passage has an outlet portion positioned in the through hole.